

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4341679

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chia-Chen Wu	03/28/2017
Pin-Hong Chen	03/28/2017
Kai-Jiun Chang	03/28/2017
I-An Huang	03/28/2017
Chih-Chieh Tsai	03/28/2017
Tzu-Chieh Chen	03/28/2017
Tsun-Min Cheng	03/28/2017
Yi-Wei Chen	03/28/2017
RECEIVING PARTY DATA	
Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
Name:	FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.
Street Address:	6TH FLOOR, PODIUM OF ELECTRIC POWER COMPANY BUILDING, MEILING STREET, JINJIANG CITY
City:	QUANZHOU CITY, FUJIAN PROVINCE
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15472308
CORRESPONDENCE DATA	
Fax Number:	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	5F., NO.389, FUHE RD., YONGHE DIST.,
Address Line 4:	NEW TAIPEI CITY, TAIWAN

PATENT

ATTORNEY DOCKET NUMBER:	NAUP2963USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	03/29/2017

Total Attachments: 16

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of Invention:
METHOD FOR FABRICATING SEMICONDUCTOR DEVICE**

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
 United States application number _____ filed on _____, or
 PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

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In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

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(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

In consideration of the payment by **Fujian Jinhua Integrated Circuit Co., Ltd.** having a postal address of _____

6th floor, Podium of electric power company building, Meiling street, Jinjiang city, Quanzhou City, Fujian province 362200, P.R.C.

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I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this MAR 28 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chia-Chen Wu

Date: MAR 28 2017

Signature: Chia-c Chia-Chen Wu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Pin-Hong Chen**

Date: **MAR 28 2017**

Signature: Pin-Hong Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Kai-Jiun Chang

Date: MAR 28 2017

Signature: kai-Jiun chang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: I-An Huang

Date: MAR 28 2017

Signature: I-An Huang

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chih-Chieh Tsai**

Date: MAR 28 2017

Signature: Chih-Chieh Tsai

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Tzu-Chieh Chen**

Date: **MAR 28 2017**

Signature: Tzu-Chieh Chen

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Inventor: **Tsun-Min Cheng**

Date: MAR 28 2017

Signature: _____

Tsun - Min Cheng

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